

## Ordering Guide

Sample Part Number: SKHC1-031-08-T100-SS-T0-F1-AIO

Chip Type	Solder Type	Sealant	Thickness Tolerance	Flatness Tolerance	Ceramic Type	Ceramic Surface
<i>SKHC1-031-08</i>						
SKHC1-031-08 31 couples, 8A max	T100	BiSn (up to 138C)	NS No Sealant	T0 ±0.1 mm	F0 ±0.05 mm	AIO Alumina (96% white) - None
	T200	CuSn (up to 227C)	SS Silicone sealant	T1 ±0.05 mm	F1 ±0.025 mm	AIN Aluminum Nitride M Metalized
			ES Epoxy Sealant	T2 ±0.025 mm	F2 ±0.0125 mm	
			CS Customer specified sealant			

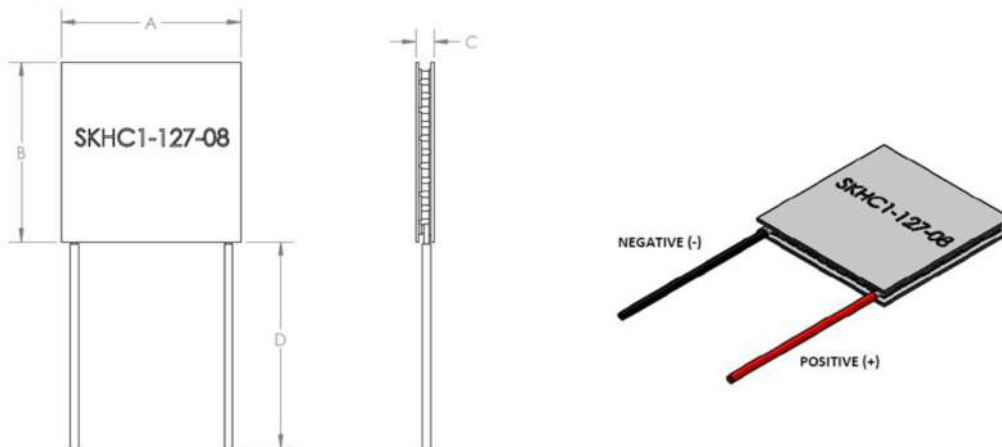
## Performance Metrics

Cat Logic	Hot Side Temp $T_h$ (°C)	$\Delta T_{max}$ (°C)	$Q_{max}$ (Watts)	$I_{max}$ (Amps)	$V_{max}$ (DC Volts)	$R_{AC}$ ( $\Omega$ )	TE Dimensions (mm)			
							A	B	C	D
SKHC1-031-08	27	74	21.7	8.5	4.1	0.36	20	20	3.5	150
SKHC1-031-08	50	83	23.3	8.5	4.4	0.39	20	20	3.5	150

### Notes:

- All performance values fall within  $\pm 10\%$  tolerance of tested data and/or models.
- Dimensions are typical and subject to change based on exact configuration ordered.
- Contact Sheetak at [info@sheetak.com](mailto:info@sheetak.com) for additional performance data, chip options or customization

## Chip Dimensions

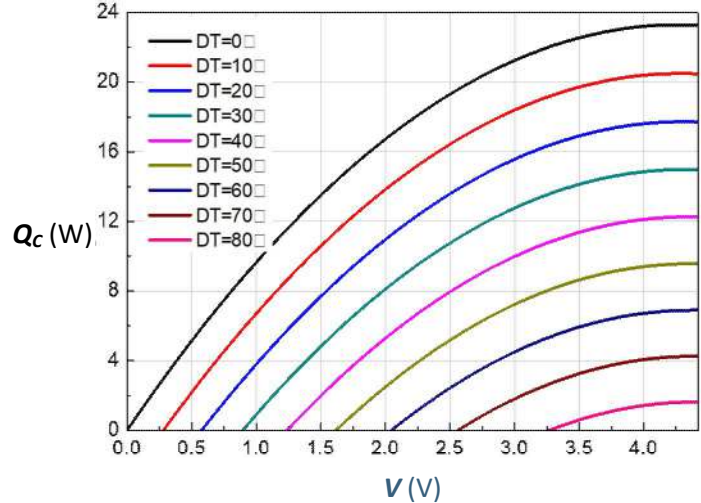
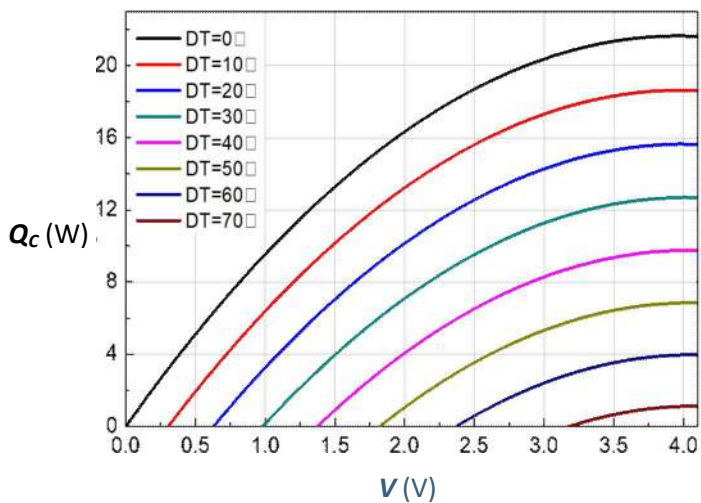
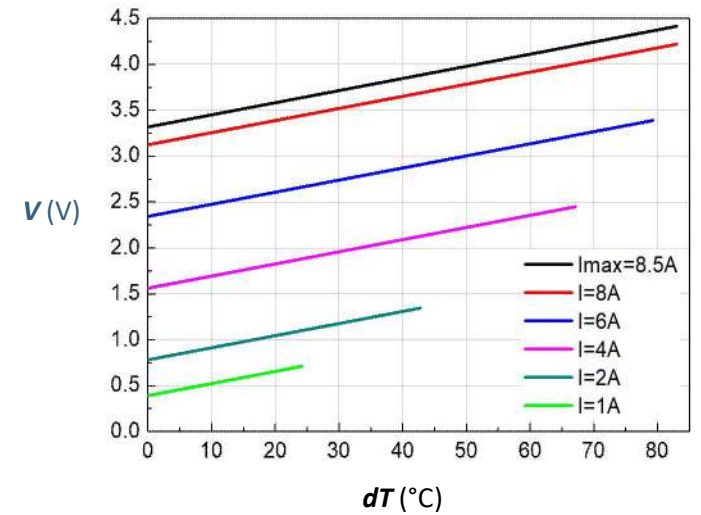
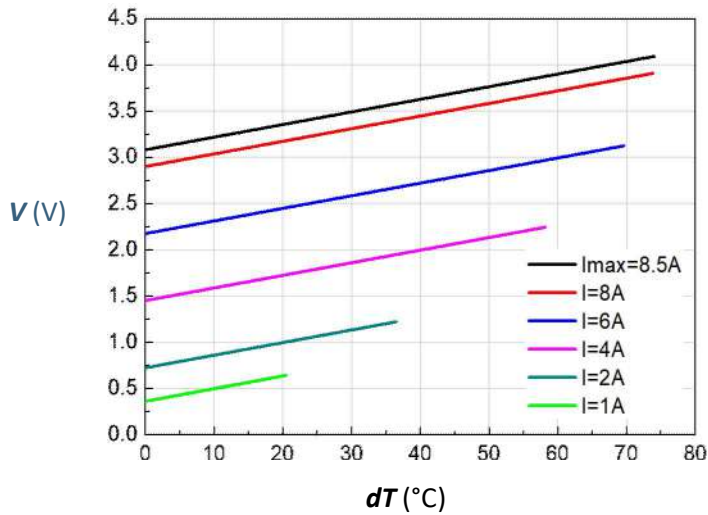
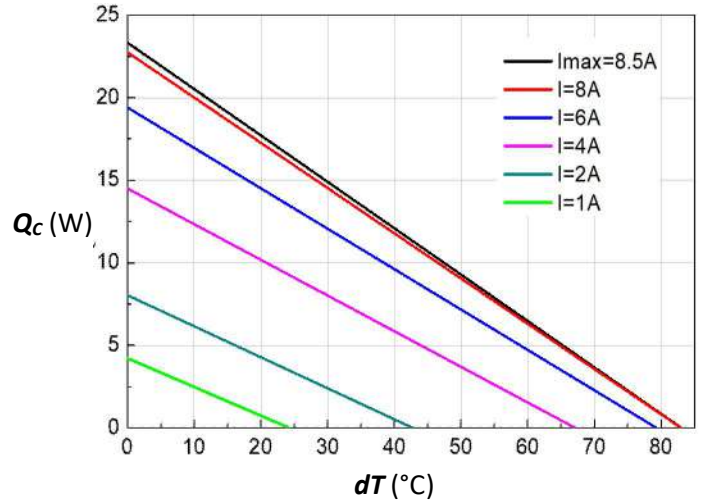
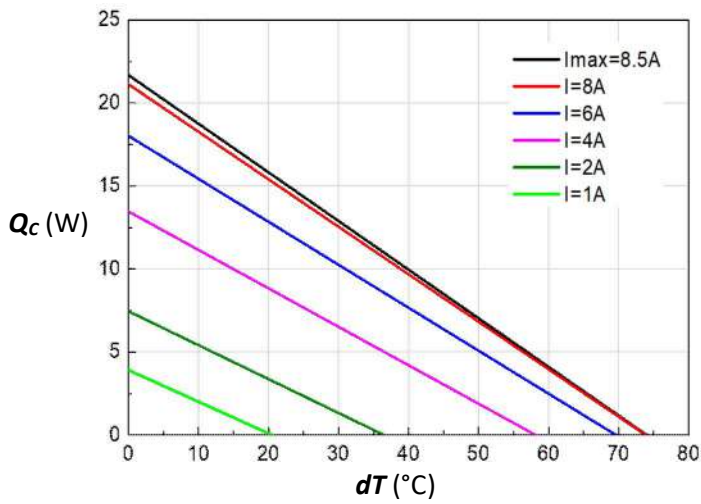


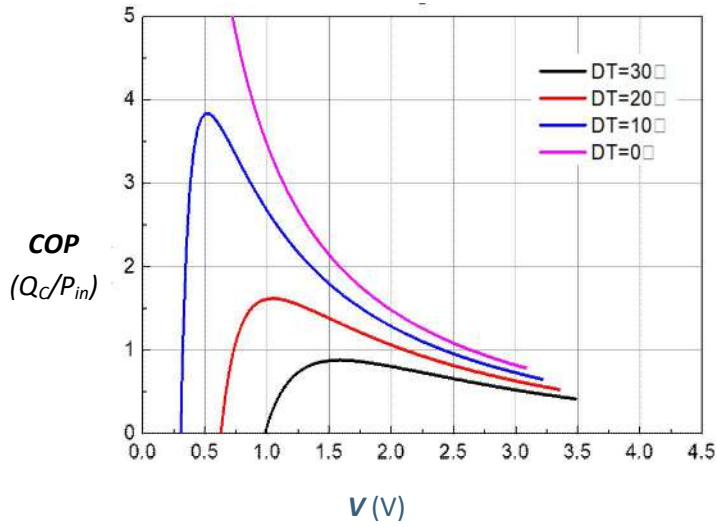
### Notes:

- Please see the *Ordering Guide* for flatness and thickness tolerances.
- Ceramic face with part number is the cold side and wires are soldered on the hot side.
- Some TECs may have a porch design or wires soldered on the side.

Performance Curves @  $T_H = 27^\circ\text{C}$

Performance Curves @  $T_H = 50^\circ\text{C}$



Performance Curves @  $T_H = 27^\circ\text{C}$ 

 Performance Curves @  $T_H = 50^\circ\text{C}$ 
